

REMARKS

Claims 10-12, 16-18, 22-30, 38, 40, 42-44, 46, 48, 50-60, 62, 64 and 66-90 are pending in the application, with claims 10, 16, 22, 25, 28, 51 and 56 being independent. Claims 10, 16 and 22 have been amended, and dependent claims 74-90 have been added.

Claims 10-12, 16-18, 22-30, 38, 40, 42-44, 46, 48, 50-60, 62, 64, and 66-73 have been rejected as being unpatentable over Imahashi in view of Celler.

With respect to independent claims 25 and 28, applicant requests reconsideration and withdrawal of this rejection because neither Imahashi, Celler, nor any combination of the two describes or suggests heating a substrate and a semiconductor film so as to deform them from flat to curved, and then flattening the substrate by cooling, as recited in each of claims 25 and 28. Applicant has been unable to find any reference to these features in Imahashi or Celler, or in the rejection. Accordingly, the rejection of claims 25 and 28, and their dependent claims, should be withdrawn.

With respect to independent claims 10, 16 and 22, applicant requests reconsideration and withdrawal of this rejection because neither Imahashi, Celler, nor any combination of the two describes or suggests a laser beam having a cross section which is elongated in one direction and which has a length of 10 cm or more, and that is irradiated while a substrate is relatively moved perpendicular to the one direction, as recited in claims 10, 16 and 22. Neither Imahashi nor Celler describes or suggests a laser beam having a length of 10 cm or more, or moving a substrate in a direction perpendicular to an elongated portion of the cross section of the laser beam. Accordingly, the rejection of claims 10, 16 and 22, and their dependent claims, should be withdrawn.

With respect to claims 51 and 56, applicant requests reconsideration and withdrawal of the rejection because neither Imahashi, Celler, nor any combination of the two describes or suggests flattening a substrate by vacuum-sucking a lower surface of the substrate using a plurality of suction inlets. The rejection concedes that Imahashi does not even describe using a vacuum to hold a substrate, and relies on Celler as showing holding a substrate with a vacuum

Applicant : Shunpei Yamazaki, et al.
Serial No. : 09/304,523
Filed : May 4, 1999
Page : 13 of 13

Attorney's Docket No.: 07977-046002 / US
3041/3050/3059/3063D1

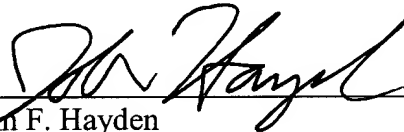
chuck during laser irradiation. Even assuming that Celler holds a substrate with a vacuum, this does not constitute flattening a substrate using suction inlets, as recited in claims 51 and 56. Moreover, contrary to the Examiner's assertion, flattening a substrate is not inherent in holding the substrate. For example, a substrate that was not flexible would not be flattened by the vacuum used to hold the substrate in place, and the vacuum necessary to hold even a flexible substrate in place may be insufficient to flatten the substrate. In addition, the pattern with which the vacuum is applied to the substrate might not result in flattening of the substrate. Accordingly, the rejection of claims 51 and 56, and their dependent claims, should be withdrawn.

Enclosed is a check in the amount of \$972 for the Request for Continued Examination fee (\$790), excess claim fees (\$72), and the Petition for Extension of Time fee (\$110). Please apply any other charges or credits to deposit account 06-1050.

Respectfully submitted,

Date: _____

10/21/04



John F. Hayden
Reg. No. 37,640

Customer No. 26171
Fish & Richardson P.C.
1425 K Street, N.W., 11th Floor
Washington, DC 20005-3500
Telephone: (202) 783-5070
Facsimile: (202) 783-2331